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(54) Title: SOLID-STATE POST-CONDENSATION PROCESS FOR INCREASING THE MOLECULAR WEIGHT OF A POLYAMIDE

(57) Abstract: The invention relates to a process for increasing the molecular weight of a polyamide via solid-state post-condensation by exposing the polyamide in the solid-state at elevated temperature to an inert gas atmosphere, that comprises a step (a) wherein the gas atmosphere to which the polyamide is exposed has a dew temperature T_{dew-1} , followed by a step (b) wherein the gas atmosphere to which the polyamide is exposed has a dew temperature T_{dew-2} , whereby T_{dew-1} is higher than T_{dew-2} . The effect is that a high molecular weight polyamide can be obtained in a shorter production time.